

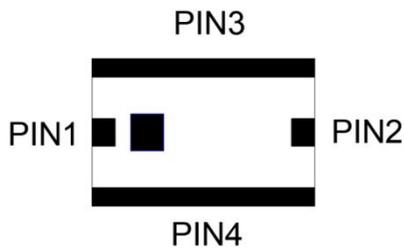
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

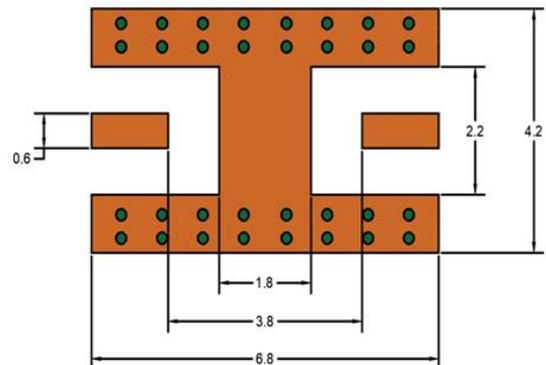
NO.	Parameter	SPEC
1	Frequency (MHz)	525~725
2	Insertion Loss (dB) @25°C EXP: 1.0	≤3.0
3	VSWR(In BW) EXP: 1.5	≤1.5
4	Ripple (dB) EXP: 0.8	≤1.0
5	Attenuation (dB)	40 dB /1dBRectangular coefficient EXP: 2.7
		1000~7000MHz EXP: 15 dB
6	Phase Linearity EXP: ±4.5°	±5°
7	Multiple phase consistency	±15°
8	Multiple amplitude consistency	±0.3 dB
9	In/Output Impedance (Ω)	50
10	Power	5W
Operating & Storage Condition (Component) Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C~ +85°C		
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity		

Construction



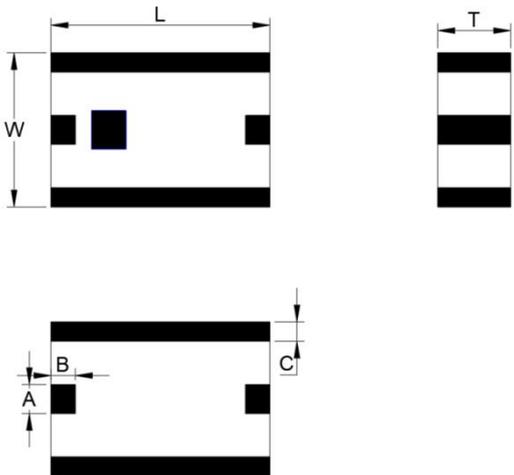
PIN	Connection
1	Input Port
2	Output Port
3	GND

Mounting Considerations

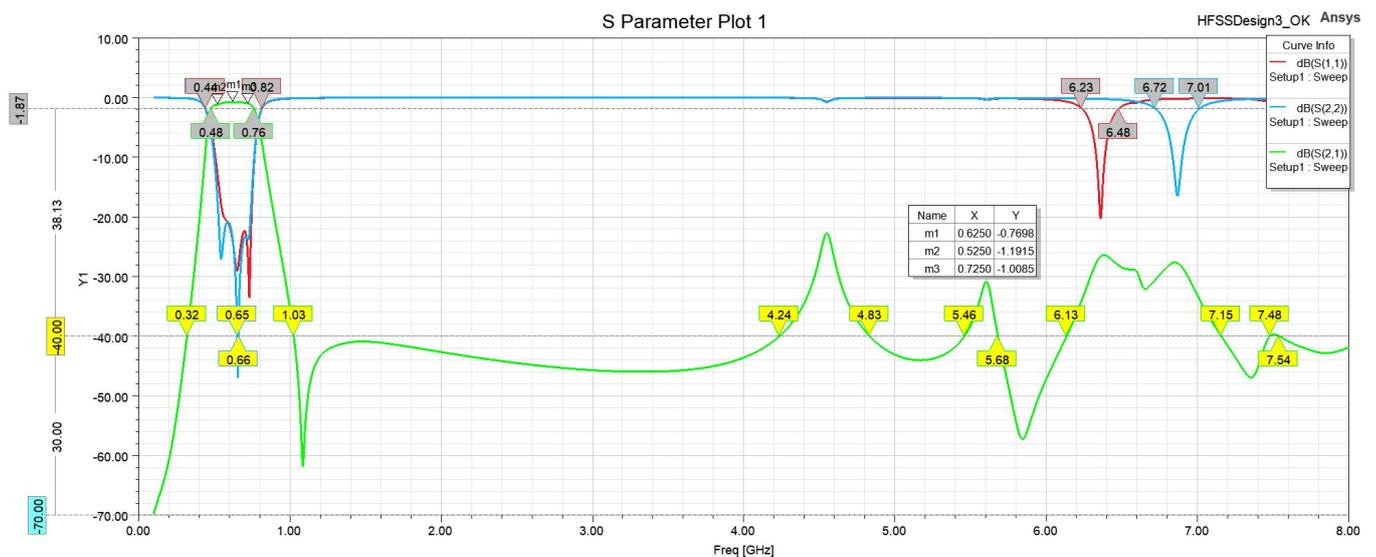


Unit: mm

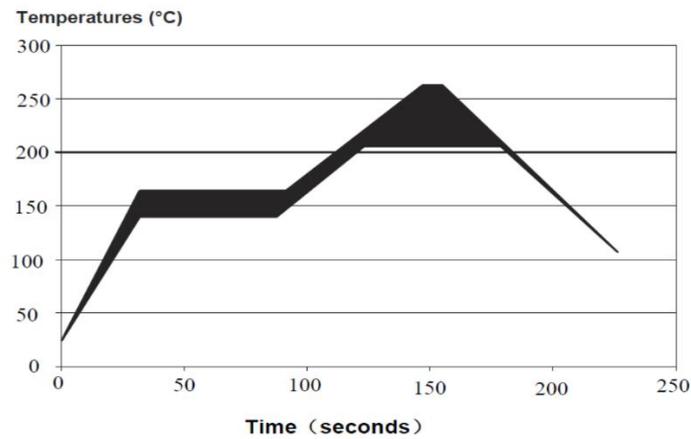
Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00±0.20
	W	3.20±0.20
	T	1.50±0.20
	A	0.60±0.10
	B	0.40±0.10
	C	0.40±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.